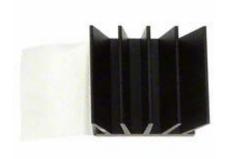
## **BGA Heat Sink - High Performance ASIC Cooling**





ATS Part#: ATS-56003-C1-R0

Description: 15.00 x 15.00 x 9.00 mm BGA Heat Sink - High Performance ASIC Cooling

Heat Sink Type: ASIC Cooling
Heat Sink Attachment: Thermal Tape
Equivalent Part Number: ATS-56003-C3-R0

\*Image above is for illustration purpose only.

## **Features & Benefits**

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- Designed specifically for ASIC package and their unique cooling requirements
- · Comes preassembled with high performance thermal interface material

## **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	12 °C/W	10 °C/W	7.8 °C/W	6.9 °C/W	6 °C/W	5.7 °C/W	5.1 °C/W
	Ducted Flow	9	N/A	N/A	N/A	N/A	N/A	N/A

## **Product Detail**

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	15.00 mm	15.00 mm	9.00 mm	17.8 mm	T412	BLACK-ANODIZED
*Image above is for illustration purpose only.	<ul> <li>Dimension</li> <li>ATS-5600</li> <li>(Saint-Go</li> <li>Thermal papplication</li> <li>ATS reserved</li> <li>ATS certifies</li> </ul>	03-C3-R0 is the exambain C675). Derformance data aren. The right to updance. The fies that this heat sire.	omponent size.  neight from the botto  ct heat sink assemble e provided for refere  ate or change its pro  nk assembly is RoHS  ustom options availa	ly with an equivalent ence only. Actual per oducts without notice S-6 and REACH cor	t thermal	interface material e may vary by



